PRODUCT DATASHEET
Rose series
last update 26/2/2015

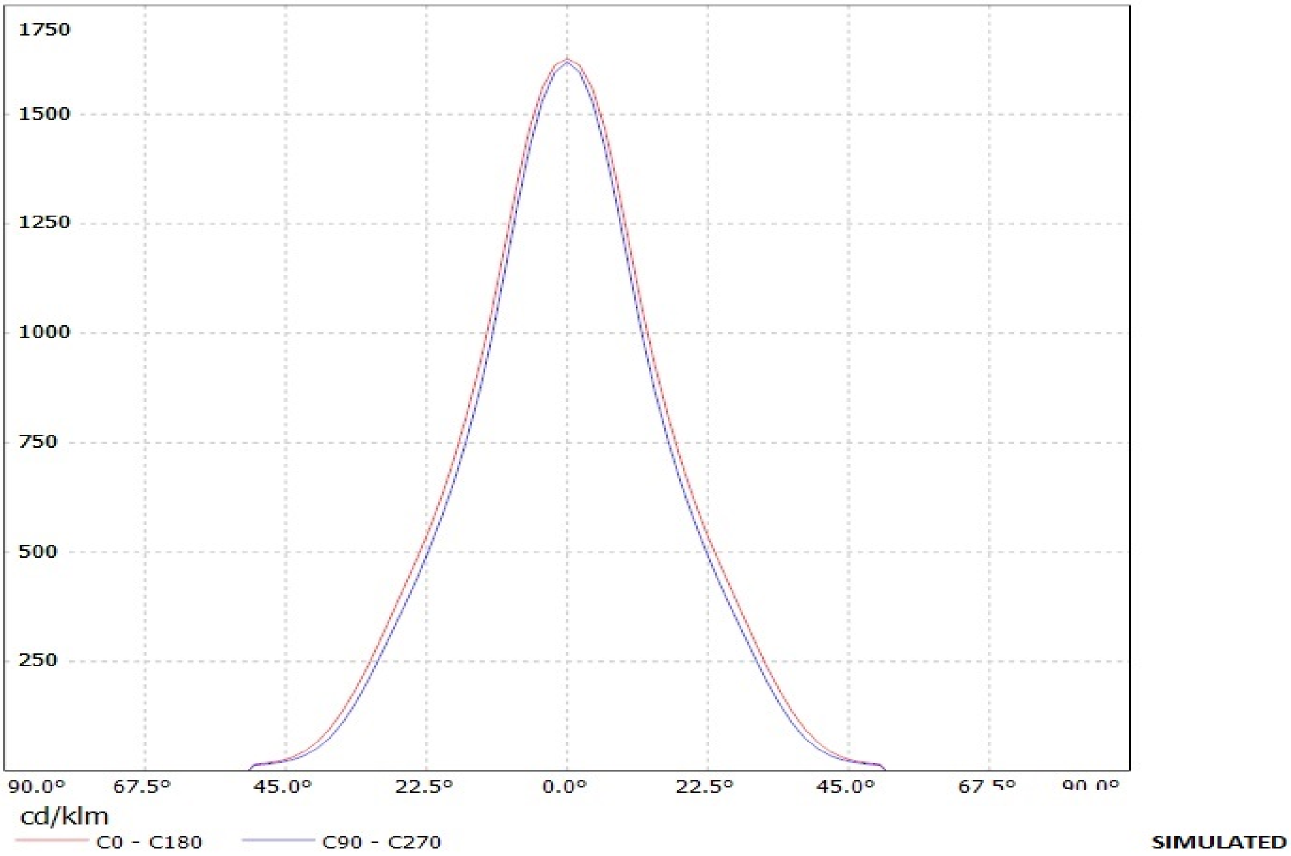
DETAILS

Product Number	FA10708_CXP-W
Family	Rose
Type	Assembly
Color	black
Diameter	21,6 + 21,6 mm
Height	13.15 mm
Style	square
Optic Material	PC
Holder Material	PC
Fastening	tape
Status	ready
ROHS Comliant	Yes
Date Updated	26/06/2013

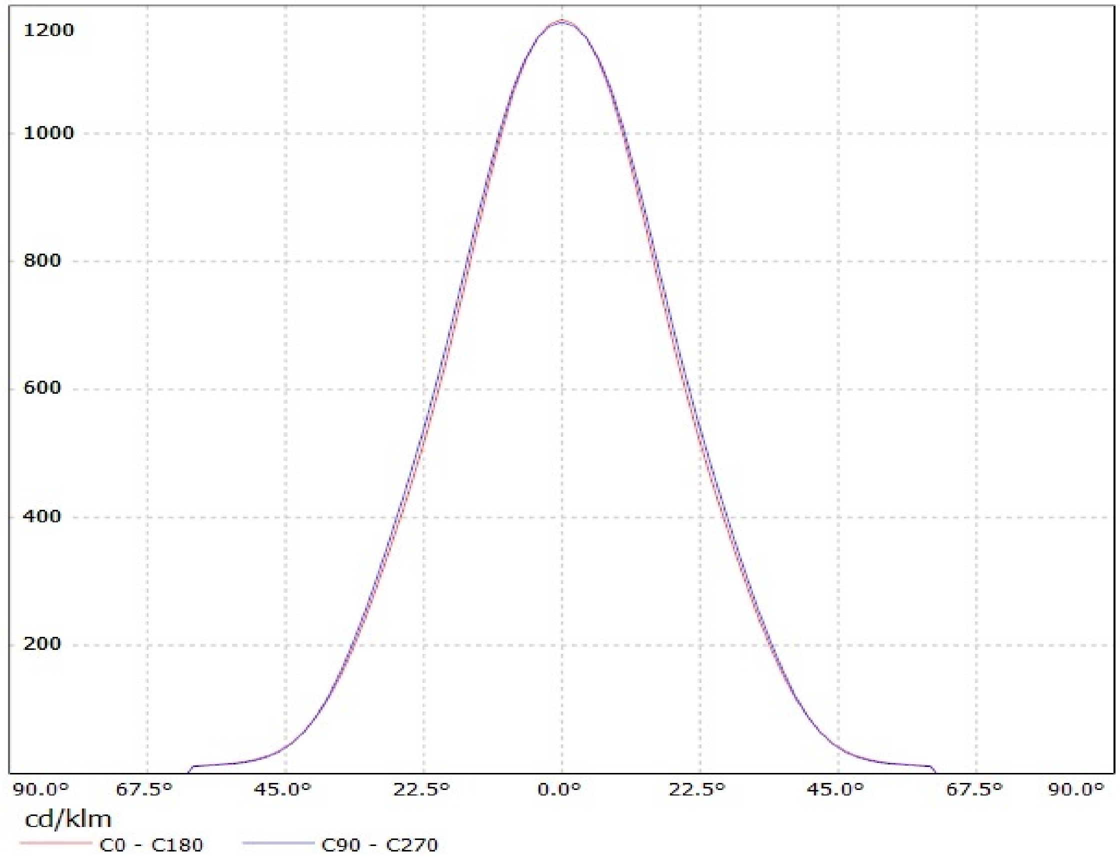
OPTICAL PROPERTIES

LED	Viewing Angle	Light Beam	Effi-ciency	cd/lm	Connector
XP-E	31 deg	Wide	79 %	1.630	-
XP-G	41 deg	Wide	77 %	1.180	-
Z5	42 deg	Wide	79 %	-	-
XP-L	48 deg	Wide	74 %	1.000	-
H35C0 (LEMWA33)	50 deg	Wide	74 %	1.000	-

Luminaire: Ledil Oy FA10708_CXP-W FA10708_CXP-W
Lamps: 1 x Cree XP-E (white)

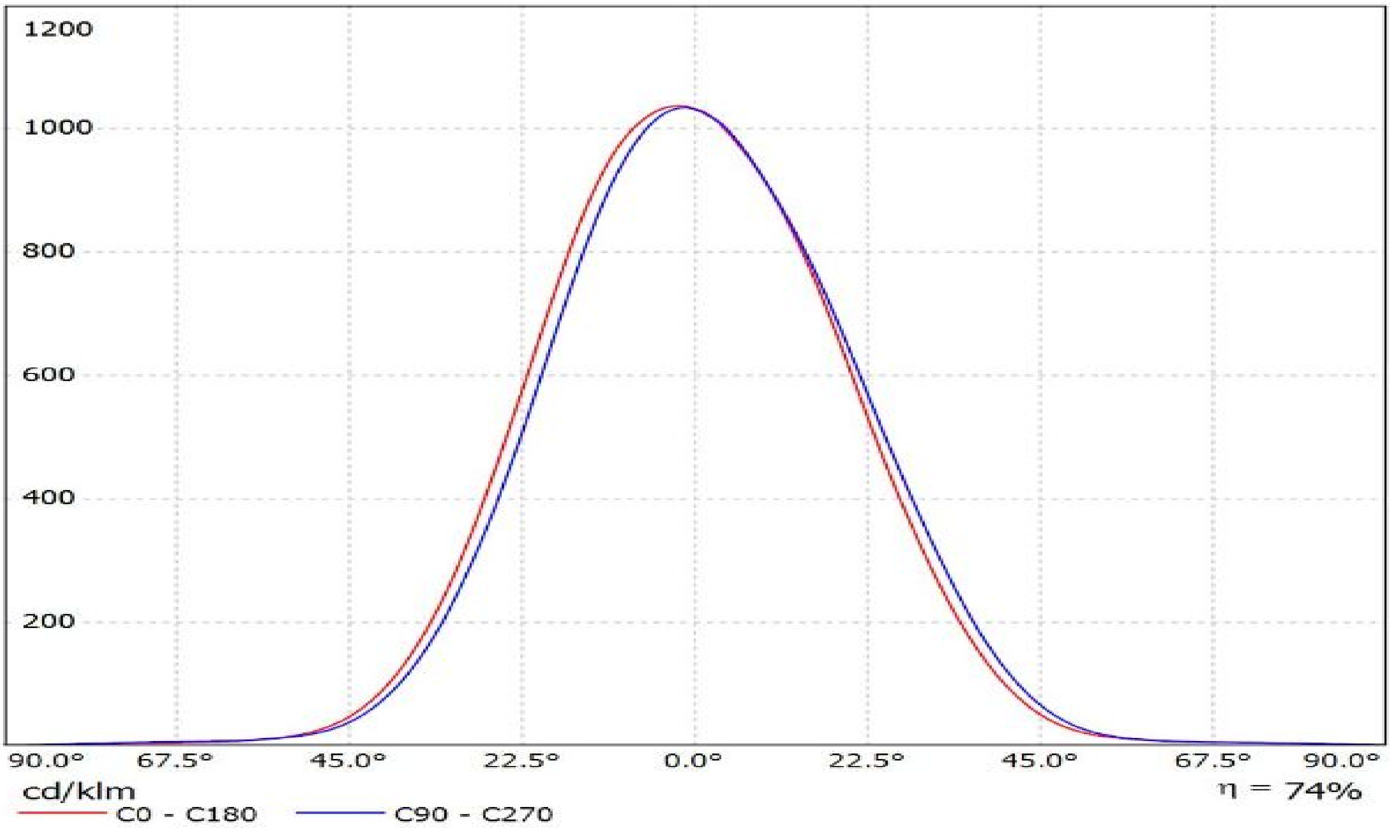


Luminaire: Ledil Oy FA10708_CXP-G-W FA10708_CXP-G-W
Lamps: 1 x Cree XP-G (White)

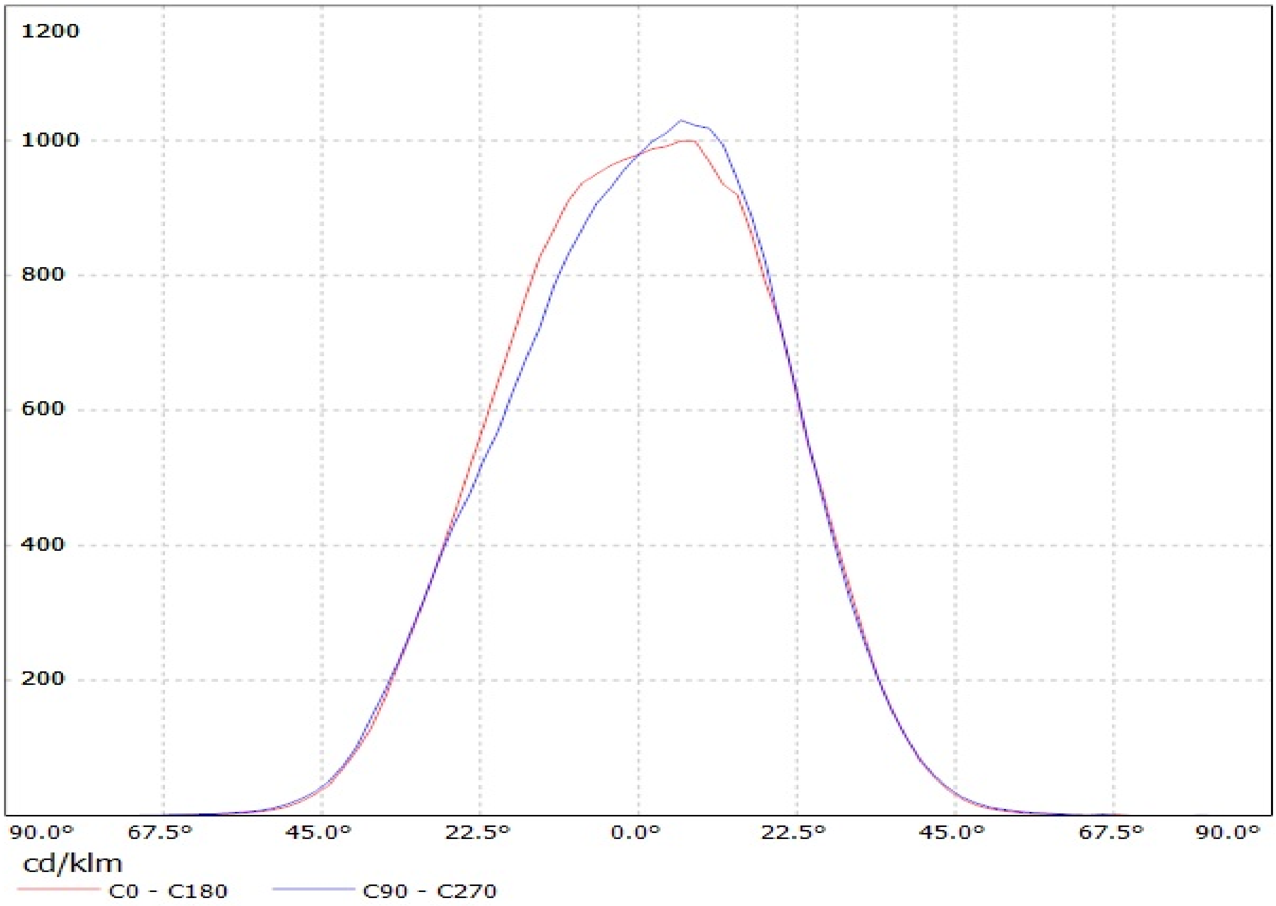


SIMULATED

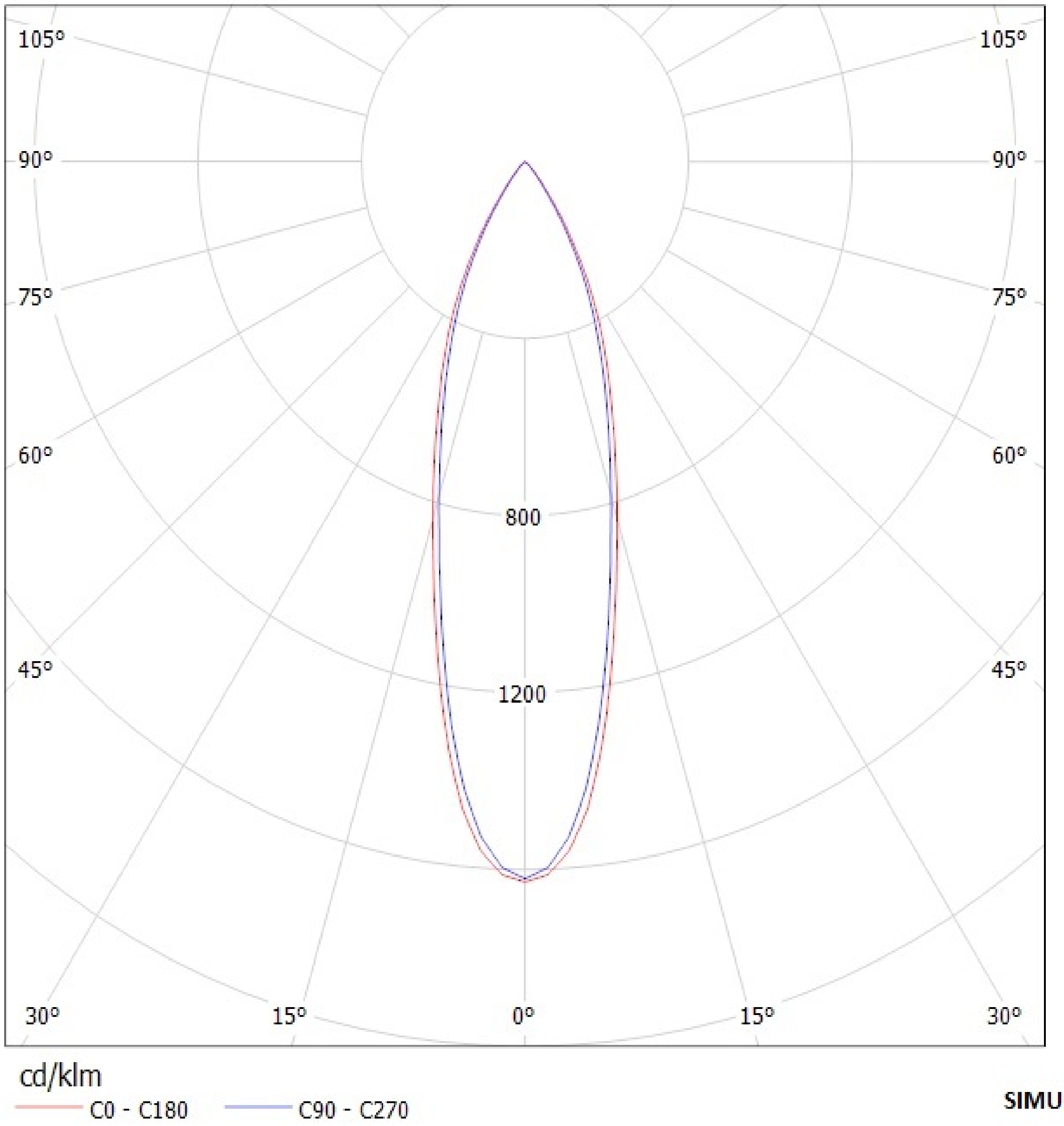
Luminaire: Ledil FA10708_CXP-W_(XP-L)
Lamps: 1 x CREE_XP-L_(XPLAWT-0-7A3-U50-0H-0001)
_107.852lm@250mA_CCT=3185K_P=0.7W_I=0.25A



Luminaire: Ledil Oy FA10708_CXP-W_(LG-3535-3W) Efficiency=74%
Lamps: 1 x LG 3535 Ceramic 3W (LEMWA33) 95lm@250mA CCT=6300K P=0.8W I=250mA



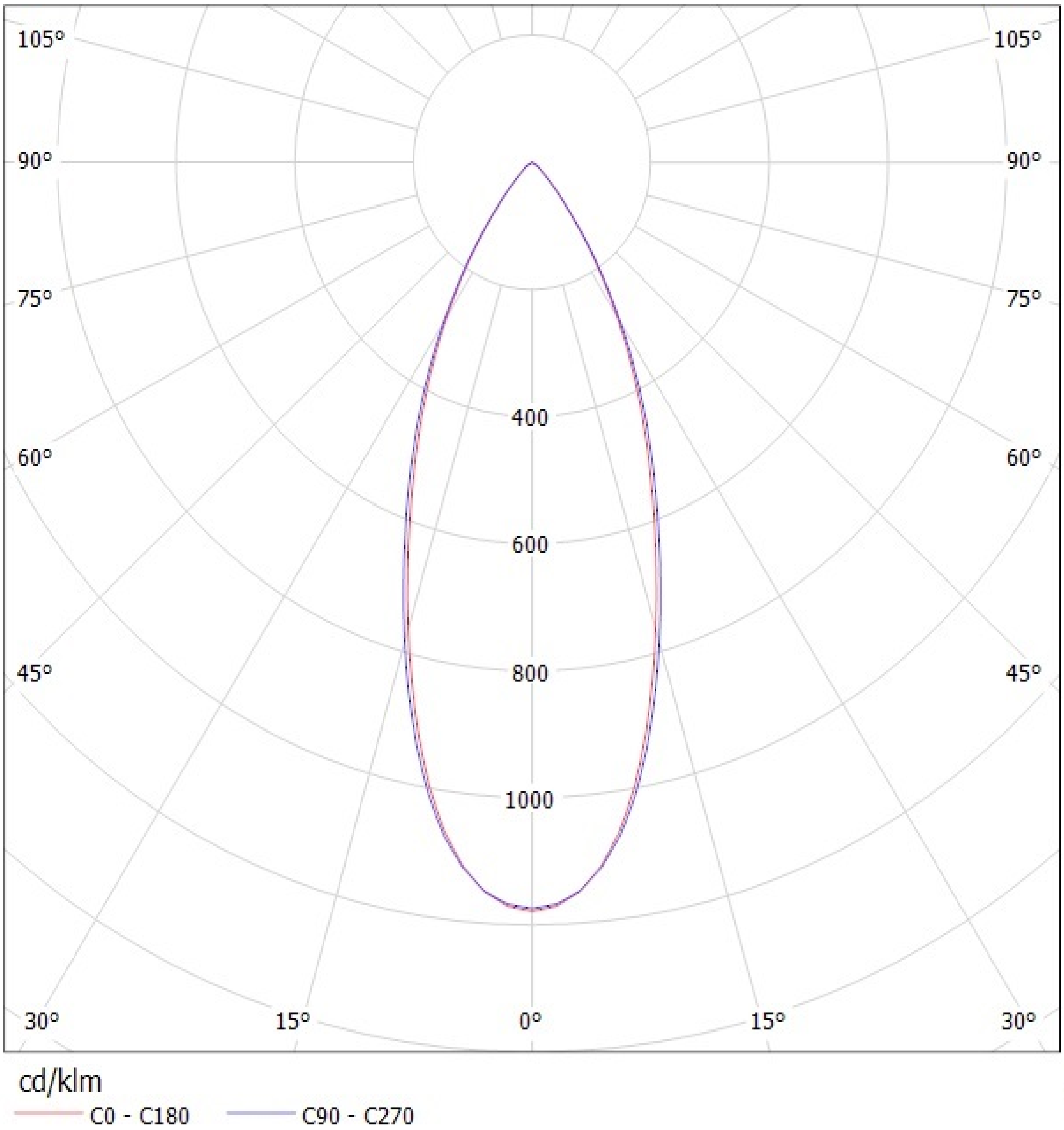
Luminaire: Ledil Oy FA10708_CXP-W FA10708_CXP-W
Lamps: 1 x Cree XP-E (white)



SIMULATED

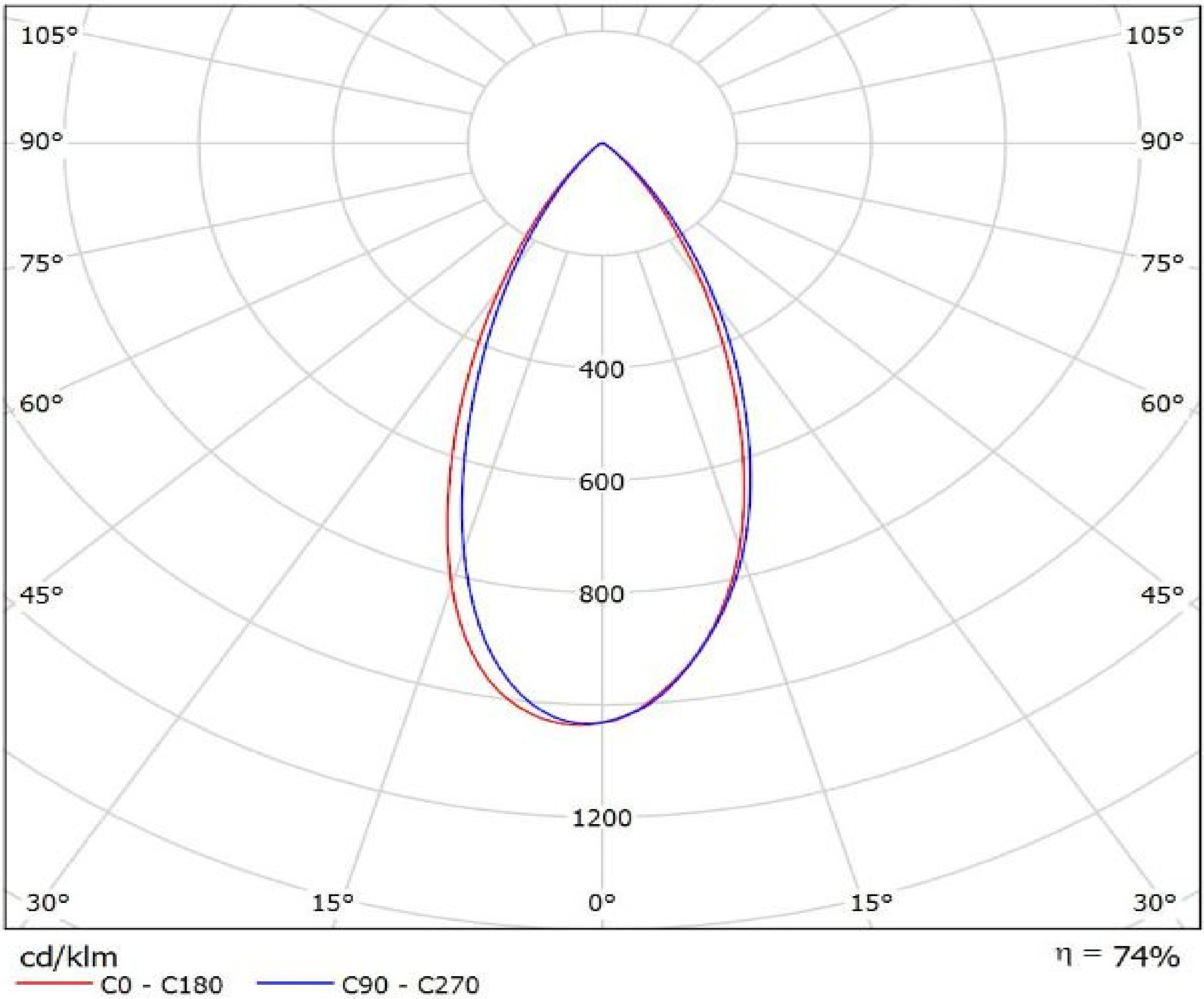
Ledil Oy FA10708_CXP-G-W FA10708_CXP-G-W / LDC (Polar)

Luminaire: Ledil Oy FA10708_CXP-G-W FA10708_CXP-G-W
Lamps: 1 x Cree XP-G (White)



SIMULATED

Luminaire: Ledil FA10708_CXP-W_(XP-L)
Lamps: 1 x CREE_XP-L_(XPLAWT-0-7A3-U50-0H-0001)
_107.852lm@250mA_CCT=3185K_P=0.7W_I=0.25A



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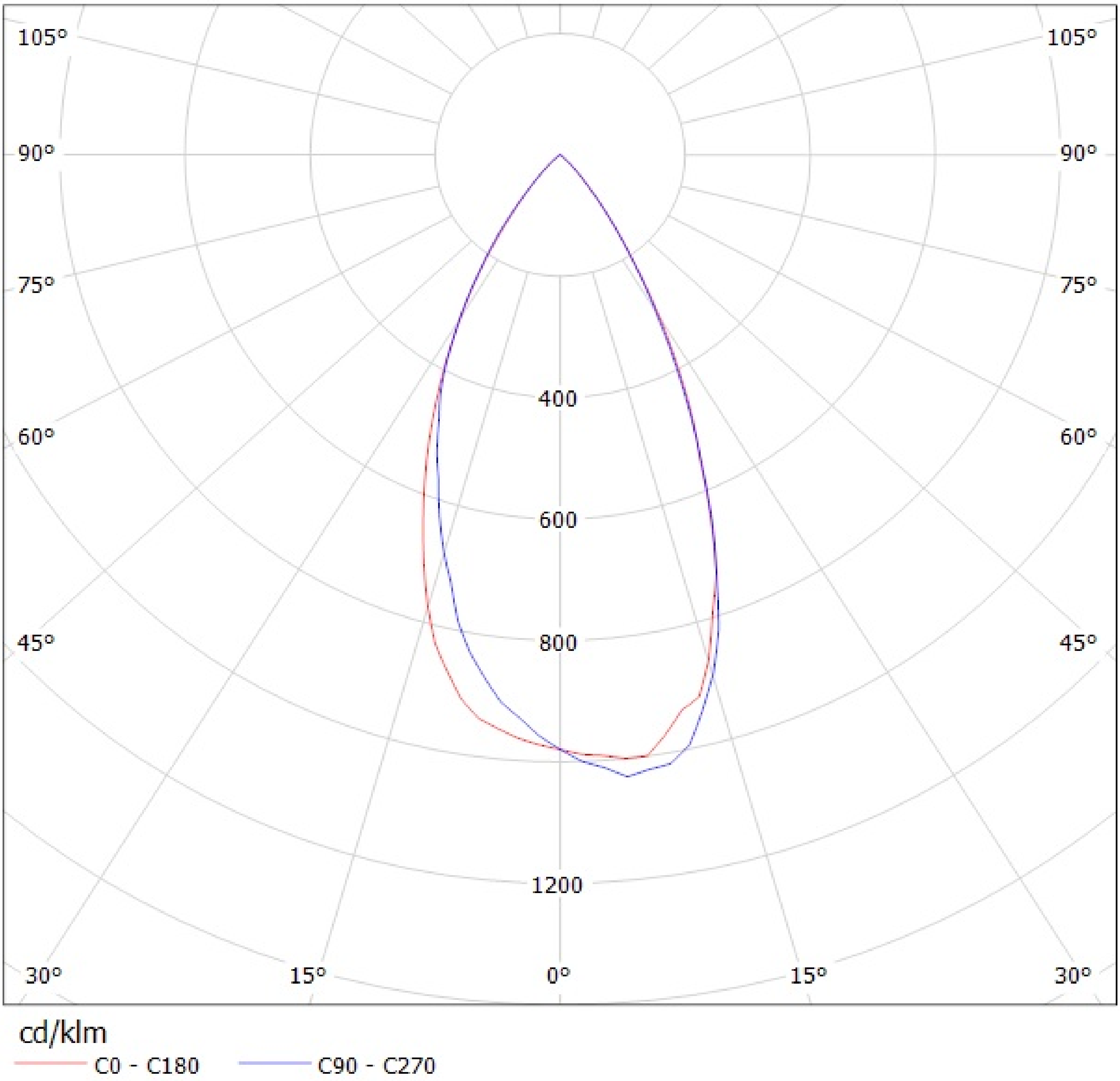
Lamps: 1 x LG 3535 Ceramic 3W (LEMWA33) 95lm@250mA CCT=6300K P=0.8W I=250mA



NOTE: The typical divergence will be changed by different color, chip size and chip position tolerance. The typical total divergence is the full angle measured where the luminous intensity is half of the peak value.

GENERAL INFORMATION

- Product series especially designed & optimized for series of LEDs.
- Special care taken to make light distribution as uniform as possible.

- Fastening to heat sink with a PU foam adhesive tape of automotive grade. Please find fastening details by clicking link: http://www.ledil.com/datasheets/DataSheet_TAPE.pdf

NOTE 1: We advise customer to ensure the suitability and sufficiency of the bond in the end product. For example, mechanical stress, vibration and holes on the surface of the circuit boar weaken the strength of the tape.

NOTE 2: Assembly to the surface must be made straight, so the tape bonds constant and balanced with fastening surface. Slanted assembly might cause unbalanced bond to the surface. All surfaces where tape is applied must be clean, dry and free from grease and dirt.

If cleaning of PCB surfaces is needed, please follow strictly the cleaning instructions of your LED manufacturer - this is important as cleaning shall under no circumstances damage LEDs or other electronics components on the PCB.

Further note that optical components shall not be cleaned with any chemicals - only micro fiber cloth may be used to remove fingerprints or other traces from handling.